Abstract of the Disclosure

A method of dividing a semiconductor wafer comprising:

a bonding film adhering step of adhering a bonding film for die bonding to the back surface of the semiconductor wafer;

a protective adhesive tape affixing step of affixing an extensible protective adhesive tape to the bonding film side of the semiconductor wafer having the bonding film on the back surface;

a dividing step of dividing the semiconductor wafer affixed to the protective adhesive tape into individual semiconductor chips by applying a laser beam along the streets;

a bonding film breaking step of breaking the bonding film for every semiconductor chip by extending the protective adhesive tape so as to give tensile force to the bonding film; and

a semiconductor chip removing step of removing the semiconductor chips having the broken bonding film from the protective adhesive tape.